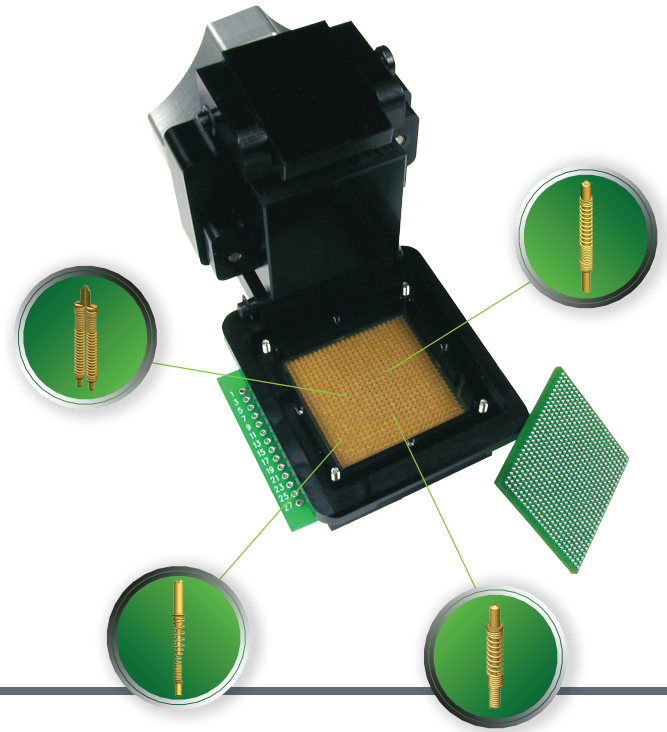




External Spring Pin Sockets for High Speed Applications



External Spring Pin (ESS) sockets allow high endurance and wide temperature range testing of 0.3mm to 1.27mm pitch BGA, LGA, QFN, QFP and SOIC devices. The unique offset external spring enables signal pass through from plunger to PCB directly without looping through inductive spring coils. These spring probes can be **customized very easily for specific test height, force, plating finish, materials, etc.**

FEATURES AND BENEFITS

Long Contact Travel	Compliance for package non-coplanarity
Gold Plated BeCu Material	High temperature applications
Small Socket Footprint	Easy to place components very near the device, i.e. tuning inductors, by pass capacitors, resistors, etc. - ideal for IC prototype and system testing and field upgradeable system designs
High Resilient Spring	Compression cycles in hundreds of thousands
Optimized Pin Diameter to Length Ratio	Impedance matched high speed applications
Solid Machined Contact	High current applications

PIN SPECIFICATION



Minimum Pitch (mm)	0.3	0.4	0.5	0.8	1
Length (mm)	3.26	2.61	3.7	3.2	3.75
DUT Side Tip Shape	Crown	Crown	Crown	Crown	Crown
PCB Side Tip Shape	Point	Round	Point	Point	Crown
DUT Side Travel (mm)	0.3	0.52	0.5	0.4	0.37
PCB Side Travel (mm)	0.15	0.19	0.2	0.2	0.33
Force (g)	15	15	24	30	40
Cres (mΩ)	100	100	50	50	30
CCC @ 125C (Amps)	2	3	4	4	7
Bandwidth (GHz @ -1dB)	10*	33.9**	16*	10*	10*
Temperature (°C)	-55 to +150°C	-55 to +150°C	-55 to +150°C	-55 to +150°C	-55 to +150°C

* estimated
** measured

ELECTRICAL PERFORMANCE: 0.4MM PITCH PIN

